



# FUTUREX series

## Introduction

Specifications and performance of HIKSEMI FUTUREX series SSD.

HIKSEMI has a sound supply chain system and perfect after-sales process. At the technical level, FUTUREX series SSD adopts advanced SSD master control and 3D NAND Flash technology, together with the NAND Flash management software independently developed by HIKSEMI, to ensure read and write speed and data security. At the product level, FUTUREX series SSDs use the highest quality 3D NAND Flash and BGA patches, which are produced by automated production lines and tested by HIKSEMI's strict standards to ensure stable service. FUTUREX series SSD can be widely used in personal computers, game consoles and other devices to provide stable and high-speed services for the target system.

## Features

- Extremely fast read and write  
PCIe interface with a maximum read speed of 7450 MB/s
- 3D NAND Technology  
3D NAND technology helps to develop higher capacity, performance, and stability
- Anti-shock and anti-fall  
No mechanical structure, using electronic chip control, data more secure.
- Application Field  
Applicable to personal computers, laptops, PS5, etc.
- Excellent Thermal Control  
with heatsink, no worries for sudden performance drops from overheating.

## Ordering Information

Capacity	Model
512GB	HS-SSD-FUTUREX 512G
1024GB	HS-SSD-FUTUREX 1024G
2048GB	HS-SSD-FUTUREX 2048G
4096GB	HS-SSD-FUTUREX 4096G

### Note

Please contact the local sales for detailed model information.

## Specification

Model	FUTUREX series			
Capacity	512GB	1024GB	2048GB	4096GB
Form Factor	M.2 2280			
Max. Seq. Read	7050 MB/s	7450 MB/s	7450 MB/s	7450MB/s
Max. Seq. Write	4200 MB/s	6600 MB/s	6750 MB/s	6500MB/s
Max. Ran 4 K Read (IOPS)	710 K	860 K	860 K	907k
Max. Ran 4 K Write (IOPS)	640 K	670 K	690 K	700k
Max. Power Consumption	3.66 W	3.92 W	3.98 W	5.44w
TBW	900TB	1800TB	3600TB	7200TB
MTBF	2,000,000 hours			
Storage Medium	3D TLC			
Interface	PCIe Gen4x4			
Working Temperature	0 °C ~ 70 °C			
Storage Temperature	-40 °C ~ 85 °C			
Function	AES-256/SM4/TCG-Opal 2.0/IEEE1667 Third-generation Agile ECC technology (4K LDPC), end-to-end data protection RAID5 & 6			
Warranty	5 years			
Weight	≤7 g			

### Note

1. Specifications are subject to change without notice.
2. 1 MB=1,000,000Bytes, 1 GB=1,000,000,000Bytes, Unformatted Capacity. User accessible capacity may vary depending on operating environment and formatting.
3. Operating Temperature (0 °C ~70 °C) is subject to SSD's S.M.A.R.T. display.

## Revision History

Version	Description	Date
V1.0.0	FUTUREX series	20230630

Data subject to change without notice.

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